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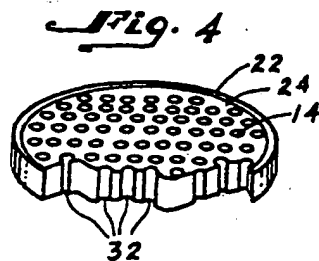
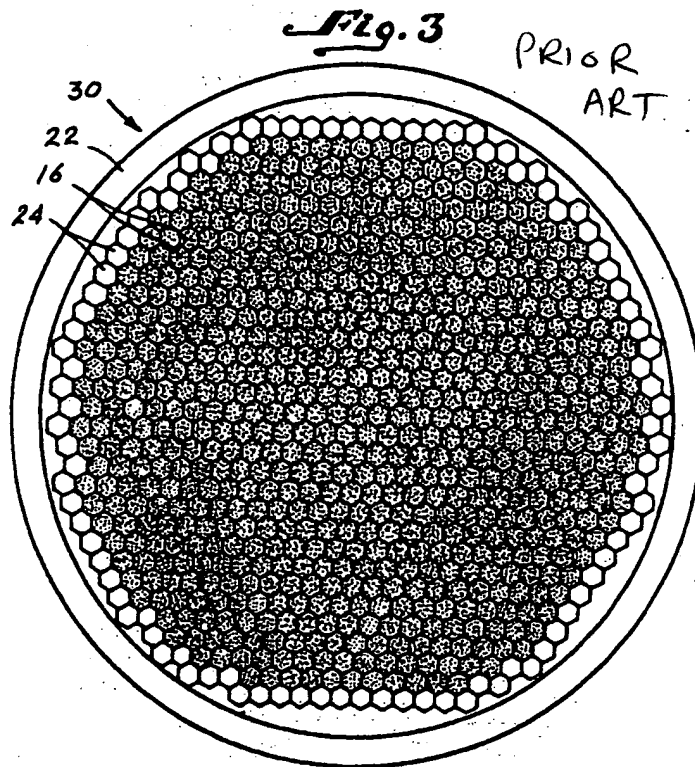
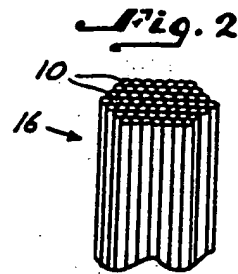
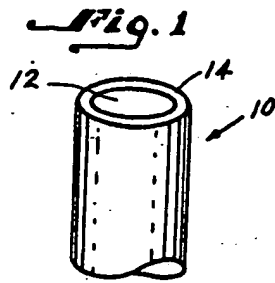
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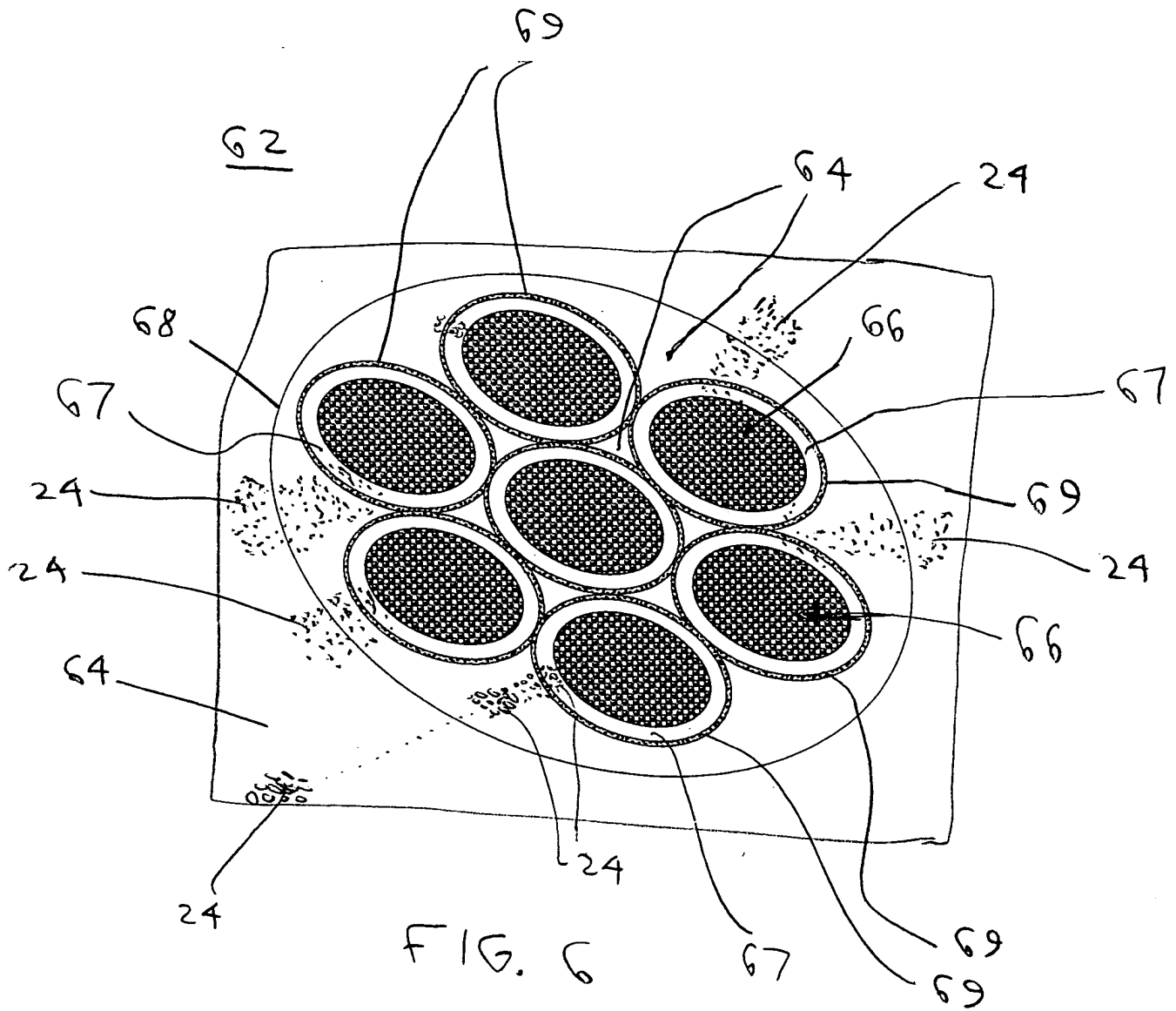
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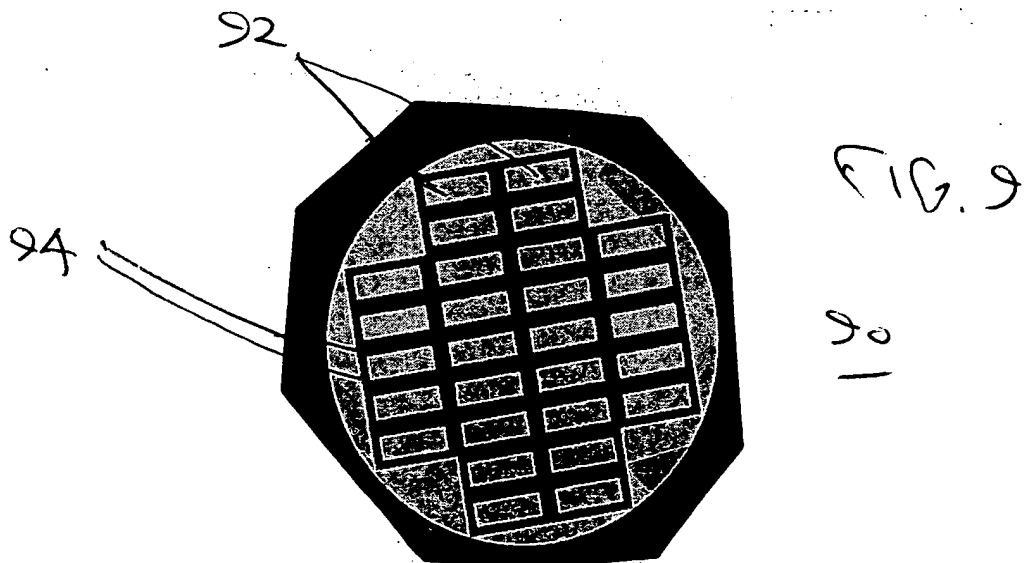
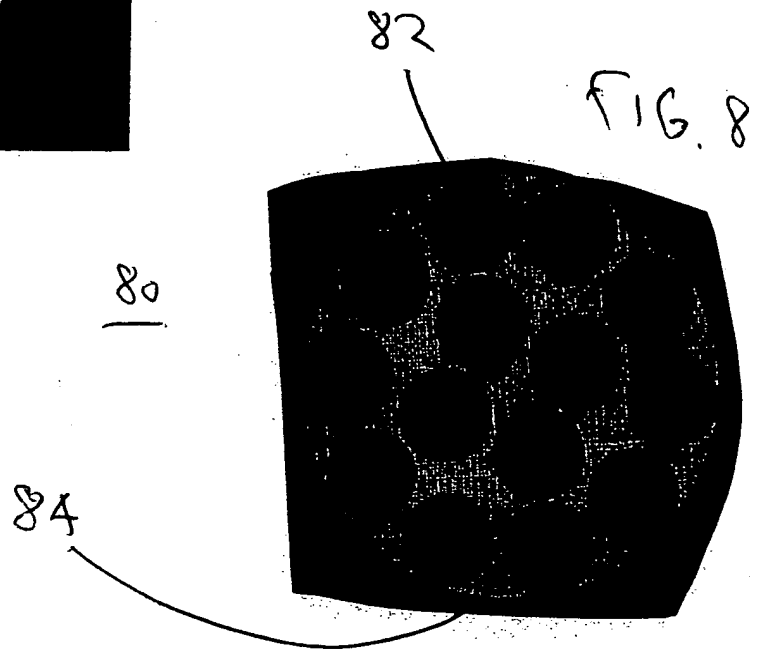
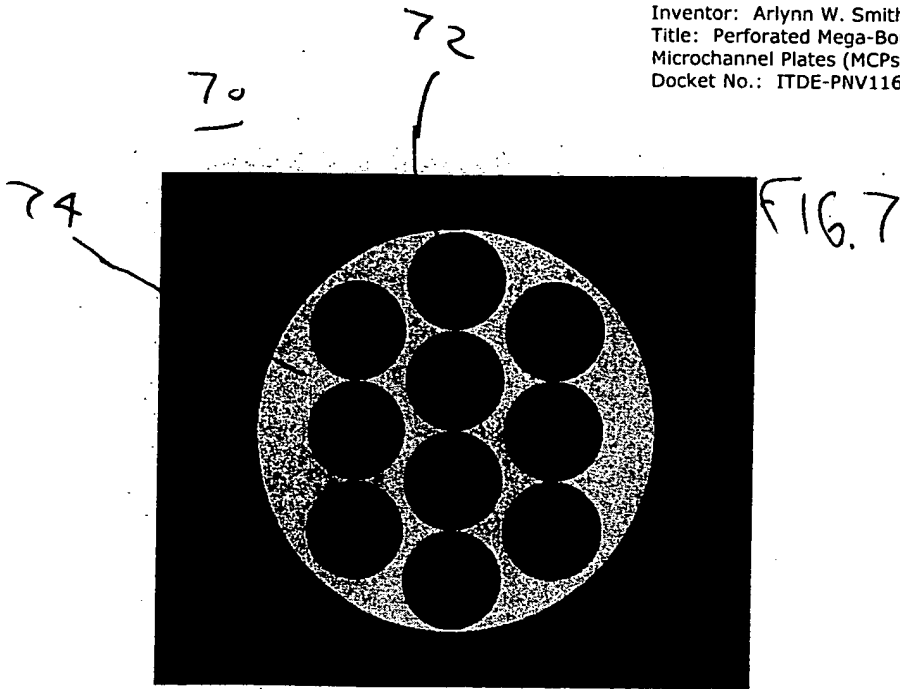


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FIG. 5

- 51 form fibers of glass core and glass cladding
- 52 form hexagonal arrays of fibers to provide bundles
- 53 stack bundles into individual cross-sectional areas, each cross-sectional area defining a mini-boule
- 54 stack non-etchable glass surrounding each mini-boule to form inner perimeter sections
- 55A stack etchable glass surrounding the stacked non-etchable glass to form outer perimeter sections
- 55B stack non-etchable glass surrounding the stacked etchable glass to form a mega-boule
- 56 press mega-boule into a monolithic stack
- 57 cut monolithic stack into a cross-sectional size compatible with semiconductor wafer fabrication tools
- 58 dice the cut monolithic stack into multiple mega-boule wafers
- 59 activate, metallize and test each mega-boule wafer, as a batch die of multiple MCPs
- 60 extract multiple MCPs from the mega-boule wafer by breaking cleave planes of the outer perimeter sections





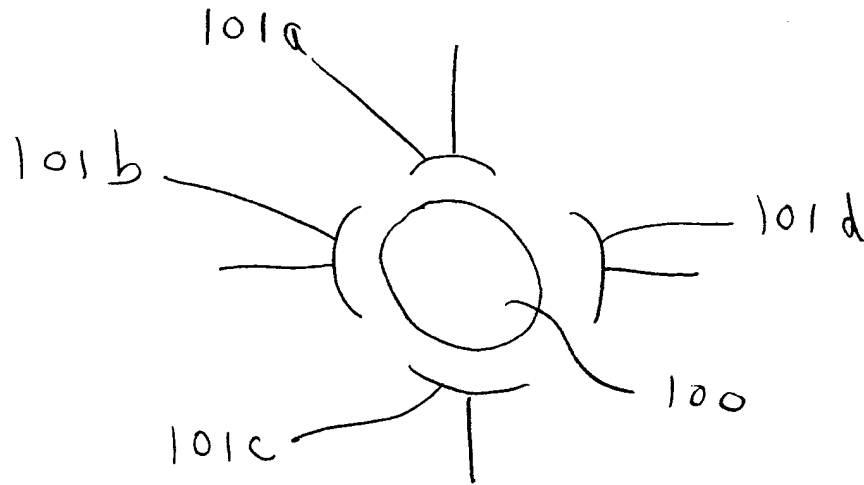


FIG. 10A

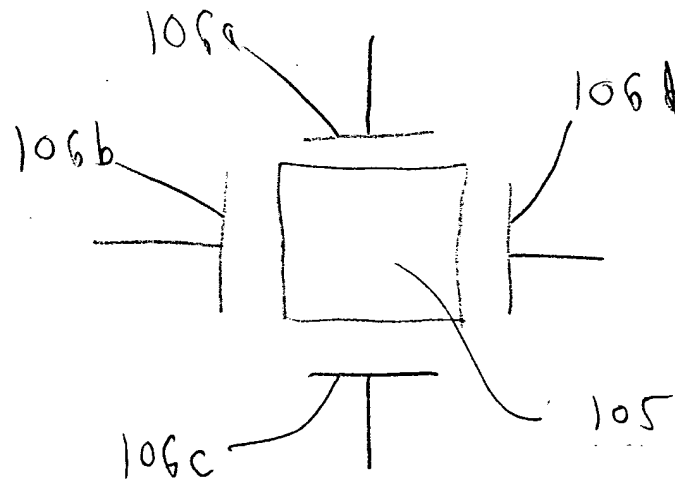


FIG. 10B

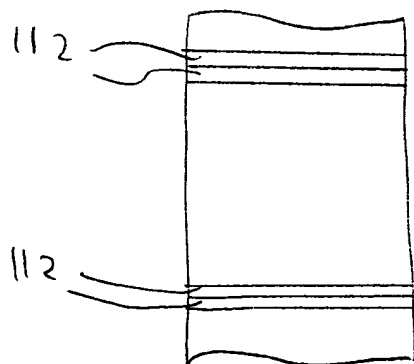


FIG. 11

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